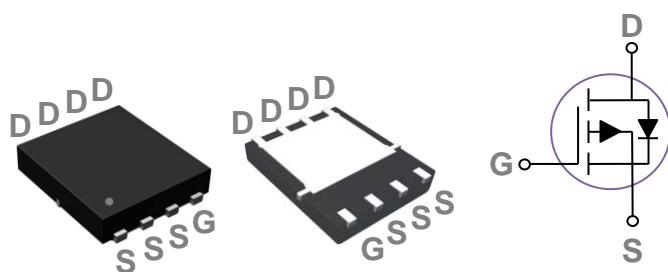


## General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

## PPAK5X6 Pin Configuration



BVDSS	RDS(ON)	ID
-60V	24mΩ	-40A

## Features

- -60V, -40A, RDS(ON) 24mΩ @VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

## Applications

- Networking
- Load Switch
- LED applications

## Absolute Maximum Ratings (T<sub>c</sub>=25 °C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-60	V
V <sub>Gs</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25 °C)	-40	A
	Drain Current – Continuous (T <sub>c</sub> =100 °C)	-26	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-160	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	105	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	-46	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25 °C)	96	W
	Power Dissipation – Derate above 25 °C	0.77	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>QJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>QJC</sub>	Thermal Resistance Junction to Case	---	1.3	°C/W



# FTK6903DFN56

## Electrical Characteristics( $T_J=25^\circ\text{C}$ ,unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-60	---	---	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{\text{DS}}=-48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

### On Characteristics

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-15\text{A}$	---	20	24	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-10\text{A}$	---	26	34	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
$\text{gfs}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_{\text{S}}=-5\text{A}$	---	15	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-20\text{A}$	---	43.8	66	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2, 3</sup>		---	4.6	7	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2, 3</sup>		---	8.3	13	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{\text{DD}}=-30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_{\text{G}}=6\Omega$ $I_{\text{D}}=-20\text{A}$	---	25	38	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	13.8	21	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2, 3</sup>		---	148	222	
$T_f$	Fall Time <sup>2, 3</sup>		---	51	77	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	2595	3893	pF
$C_{\text{oss}}$	Output Capacitance		---	162	243	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	115	173	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	8	---	$\Omega$

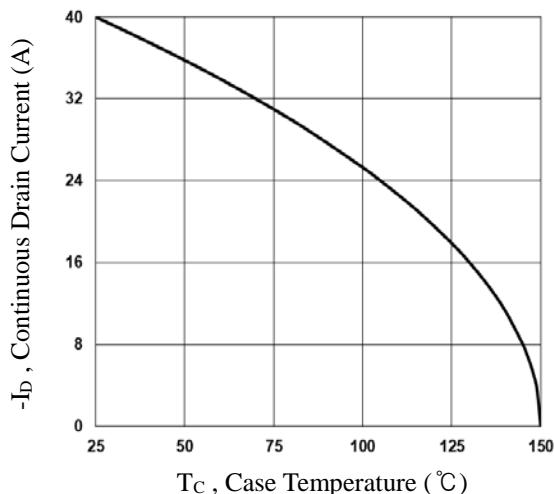
### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-40	A
			---	---	-80	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_R=-50\text{V}$ , $I_{\text{S}}=-10\text{A}$	---	40	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$di/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	30	---	nC

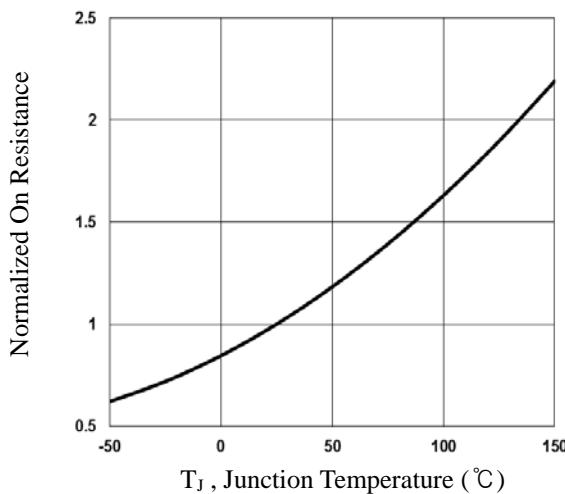
Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- $V_{\text{DD}}=-25\text{V}$ ,  $V_{\text{GS}}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=-46\text{A}$ . Starting  $T_J=25^\circ\text{C}$
- The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
- Essentially independent of operating temperature.

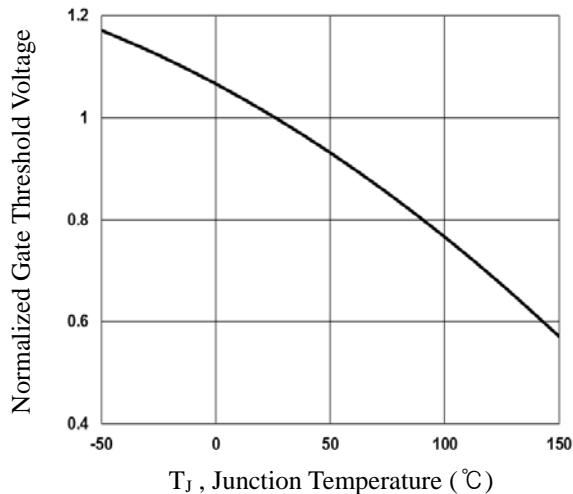
## 60V P-Channel MOSFETs



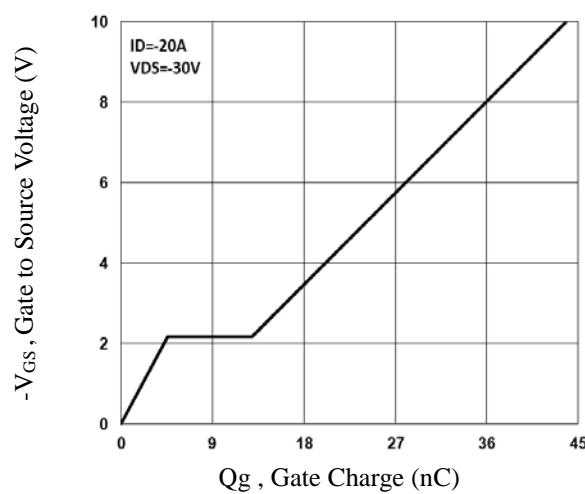
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



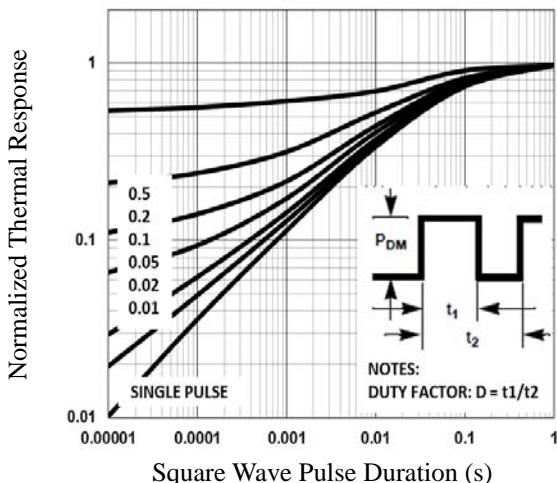
**Fig.2 Normalized R<sub>DSON</sub> vs. T<sub>j</sub>**



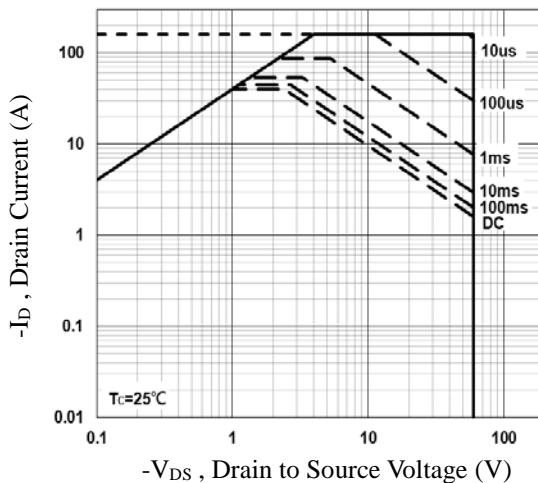
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



**Fig.4 Gate Charge Characteristics**



**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

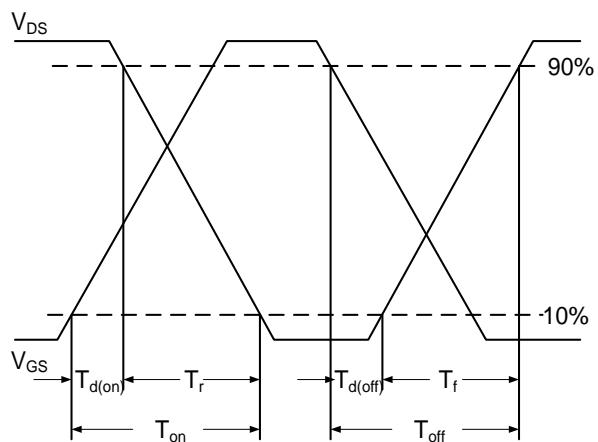


Fig.7 Switching Time Waveform

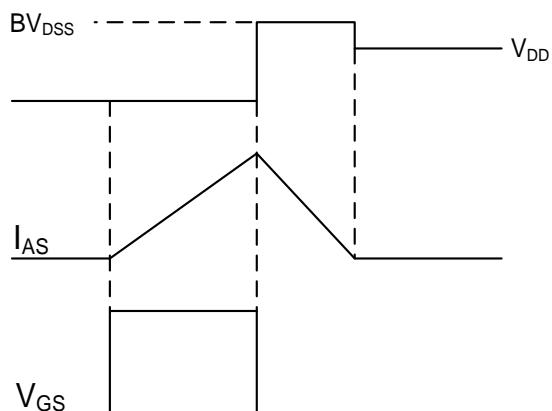
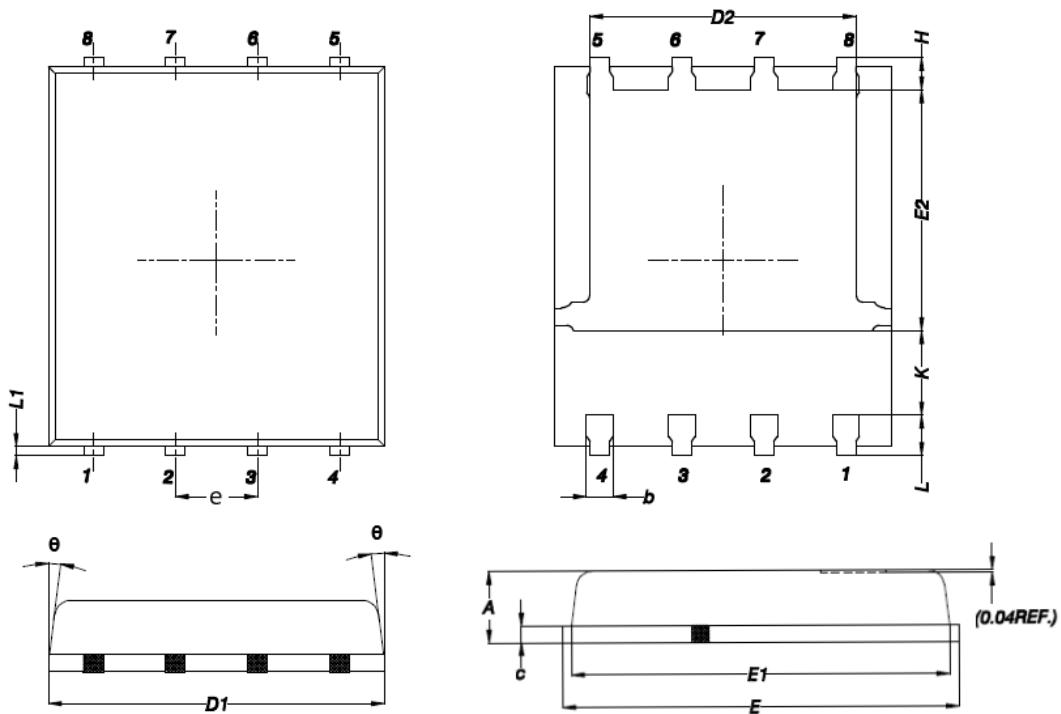


Fig.8 EAS Waveform

## PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.200	0.850	0.047	0.031
b	0.510	0.300	0.020	0.012
C	0.300	0.200	0.012	0.008
D1	5.400	4.800	0.212	0.189
D2	4.310	3.610	0.170	0.142
E	6.300	5.850	0.248	0.230
E1	5.960	5.450	0.235	0.215
E2	3.920	3.300	0.154	0.130
e	1.27BSC		0.05BSC	
H	0.650	0.380	0.026	0.015
K	---	1.100	---	0.043
L	0.710	0.380	0.028	0.015
L1	0.250	0.050	0.009	0.002
θ	12°	0°	12°	0°